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Advances in Hydrogels and Hydrogel-Based Composites

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

This Special Issue is dedicated to showcasing the recent developments in both bare hydrogels and hydrogel composites with high performance and multifunctionality. Furthermore, we welcome contributions that highlight application examples of hydrogel-based systems tailored to specific fields or that pave the way for new fields of study.

Dr. Gi Doo Cha Guest Editor







IMPACT FACTOR 4.6





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Editor-in-Chief

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Message from the Editor-in-Chief

Gels (ISSN 2310-2861) is recently established international, open access journal on physical and chemical gel-based materials. The journal aim is to encourage scientists to publish their experimental and theoretical results in as much detail as possible. General topics include but not limited to synthesis, characterization and applications of new organogels, hydrogels and ionic gels made either from low molecular weight compounds or polymers, composite and hybrid materials where a metal is by some means incorporated into the gel network, and computational studies of these materials in order to provide a better understanding of gelation mechanism. We cordially invite you to consider publishing with us and contribute with your own grain of sand to the advance in this fascinating field.

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